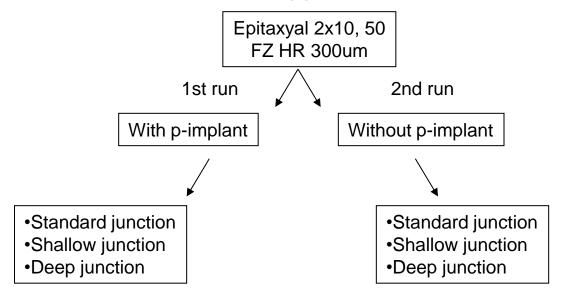
# Status of RD50 projects

Giulio Pellegrini



### Status of the project:

Fabrication of new p-type pixel detectors with enhanced multiplication effect in the n-type electrodes



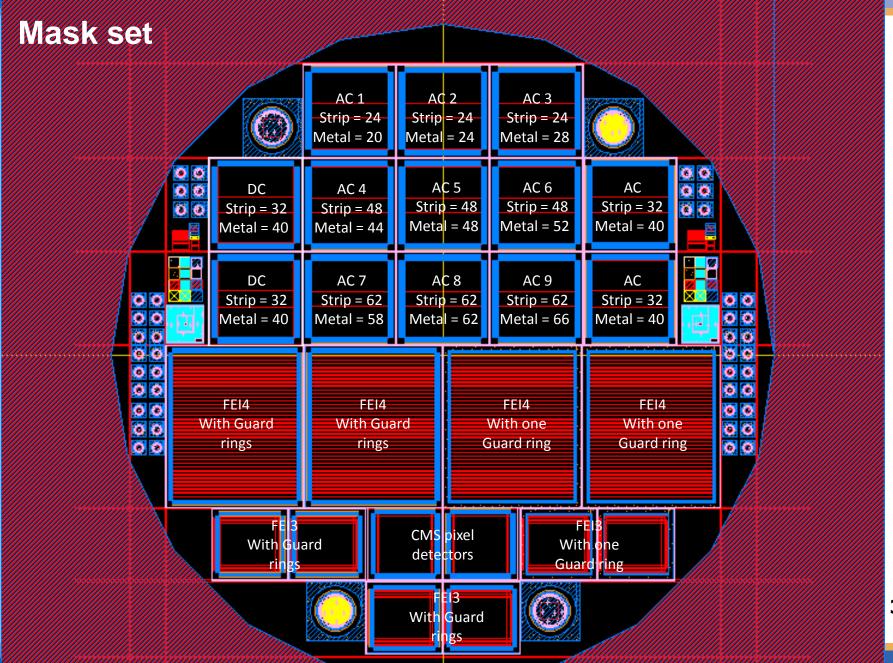
12 wafers + 2 epi without p-stop

12 wafers + 2 epi without p-stop

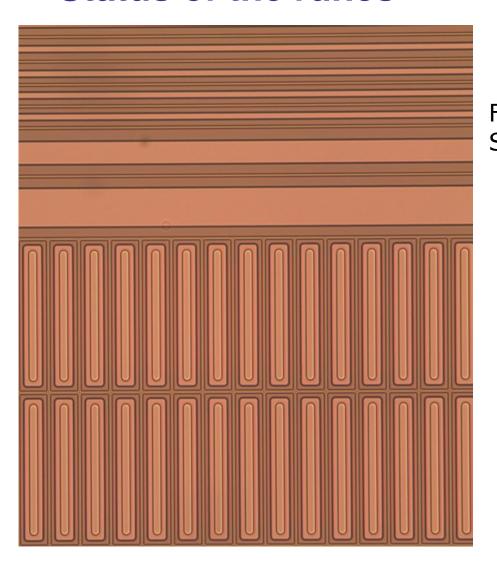
#### Total of 28 wafers to be fabricated.

Epitaxial wafer with 10um active substrate will be only fabricated with shallow junction due to the high diffusion of the dopants.



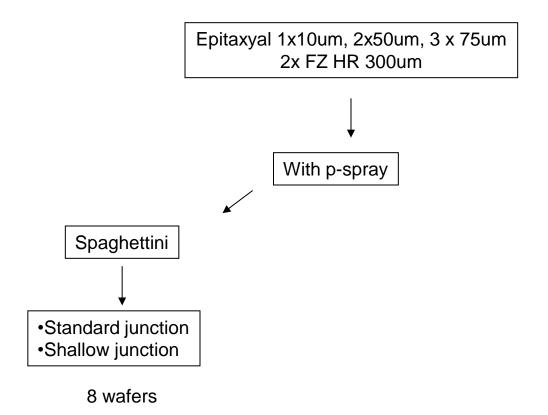


#### Status of the runes



First run: Doping polysilicon (56/100) Second run: Metal deposition(50/80)

## 3rd run with Spaghettini



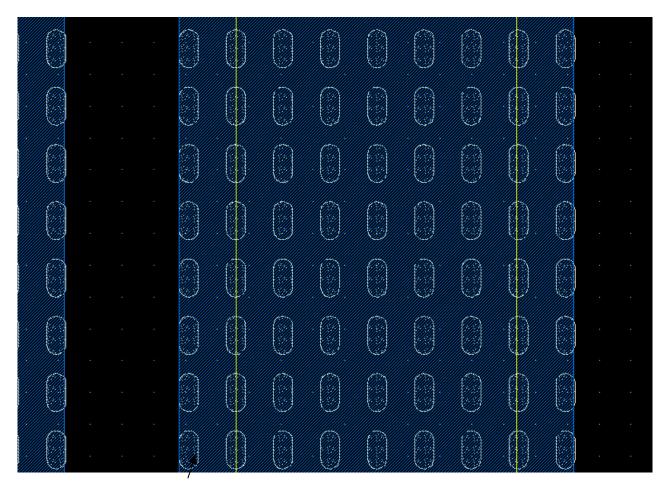
Total of 8 wafers to be fabricated.

Epitaxial wafer with 10um active substrate will be only fabricated with shallow junction due to the high diffusion of the dopants.

Run is ready to start.



## Spaghettini (strips and pixels)

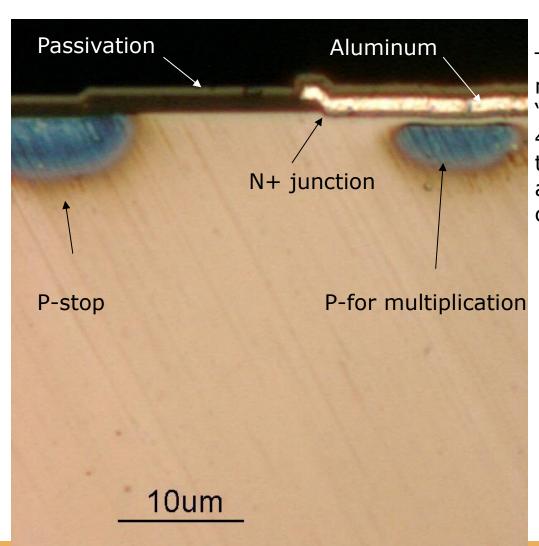


N+ diffusion (3x6um<sup>2</sup>), pitch 4um.

Idea from Gregor's talk: Charge collection studies on heavily irradiated "spaghetti" diodes



### **Technology**



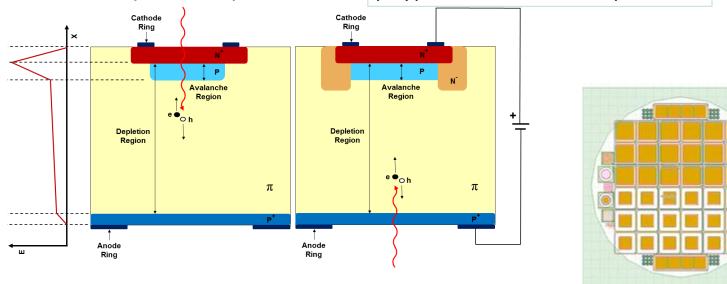
The n+ implant does not diffuse much into the bulk, <1um. The "spaghettini" are separated by 4um in order to avoid the short of the implants. The p+ diffuse quite lot, 5-6 um so it is not compatible with this geometry.

# **New RD50 funding request**

**Title of project:** Fabrication of 200um thick p and n- type pad detectors with enhanced multiplication effect.

Request to RD50: 10.000€ (12.500 CHF)
Total project cost: 20.000€ (25.000CHF)

*n-type wafers=> h+ multiplication p-type wafers=> e- multiplication* 

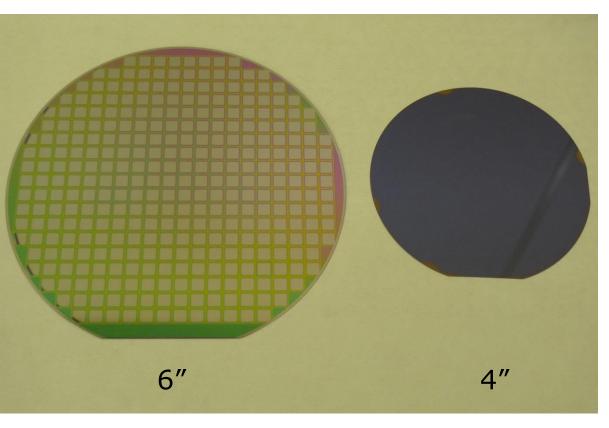


This fabrication run will be also used to understand and to improve the relatively low yield of the first fabrication of diodes with multiplication

- Pixel detectors applications
- Future linear collider



#### Future work: 6" wafers fabrication



N-p diodes 5x5mm<sup>2</sup> 300um thick p-spray isolation Mask made by stepper At metallization step, ready at the end of July.